



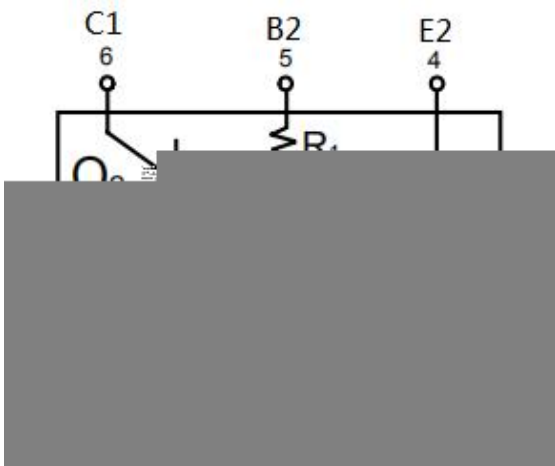


**/ D**

SOT-363            NPN+PNP  
Double silicon NPN and PNP transistor in a SOT-363 Plastic Package

With built-in bias resistors, simplify circuit design, reduce a quantity of parts and manufacturing process, Halogen-free Product.

Switching applications, interface circuit and driver circuit applications.



**/ h<sub>FE</sub> Classifications & Marking**

Marking	H314
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Parameter	Symbol	Rating	Unit
Output Voltage	$V_{CC}$	50	V
Input Voltage	$V_{IN}$	40	V
		-6	V
Output Current	$I_C$	100	$mA^{\text{D}}$
	$I_O$	70	mA
Power Dissipation	$P_C$	200	mW
Junction Temperature	$T_j$	150	$^{\circ}C$
55 Storage Temperature Range	$T_{stg}$	-55~150	$^{\circ}C$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage(OFF)	$V_{I(off)}$	$v_{CC}=5.0V$ $I_O=100\mu A$			0.3	V
Input Voltage(ON)	$V_{I(on)}$	$v_{CC}=5.0V$ $I_O=1mA$	1.4			V
Output Voltage	$V_{O(on)}$	$I_O=5mA$ $I_I=0.25mA$		0.1	0.3	V

2

v  
I

v

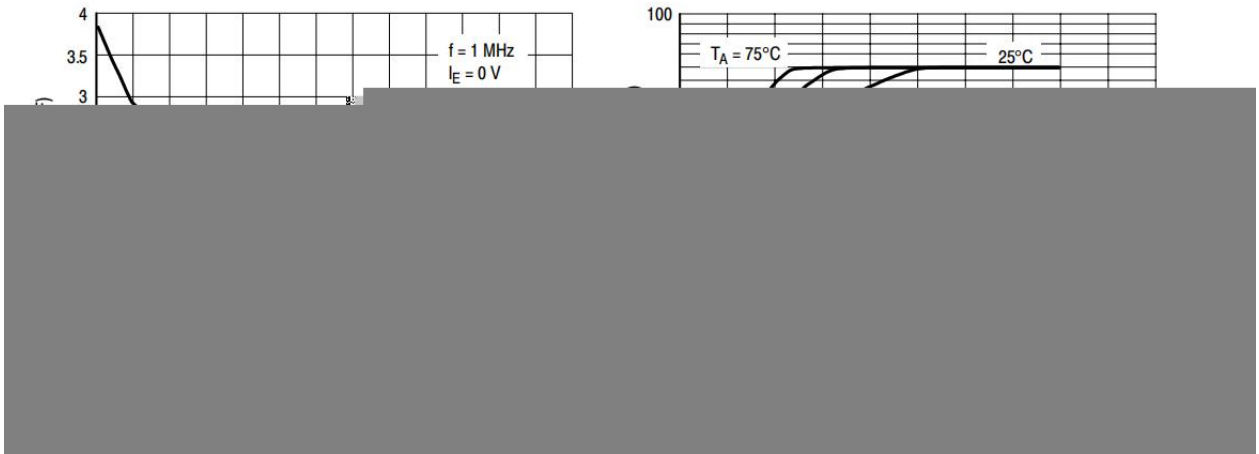
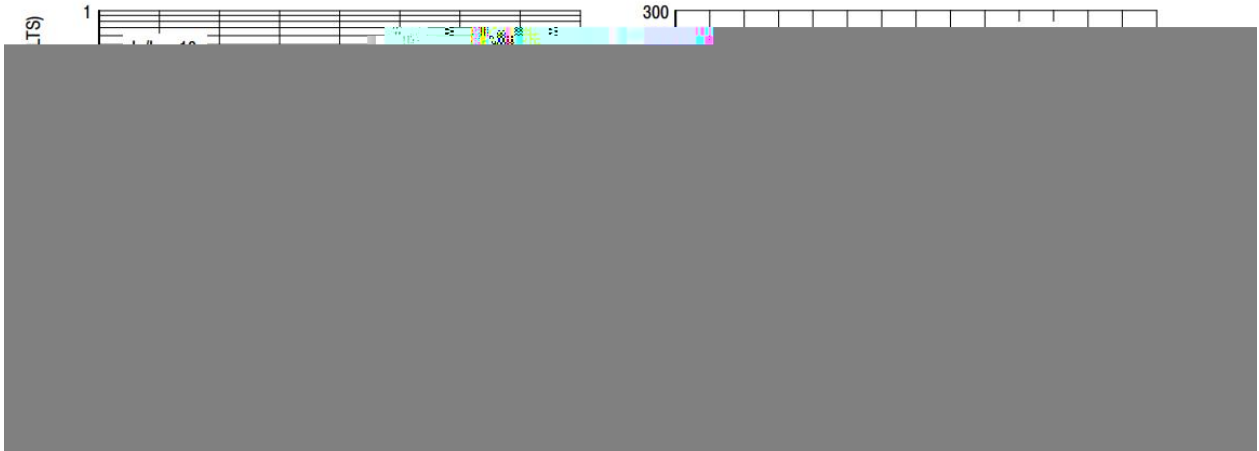
v



Parameter	Symbol	Rating	Unit
Output Voltage	$V_{CC}$	-50	V
Input Voltage	$V_{IN}$	-40	V
		6.0	V
Output Current	$I_C$	-100	mA
	$I_O$	-70	mA
Power Dissipation	$P_C$	200	mW
Junction Temperature	$T_j$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage(OFF)	$V_{I(off)}$	$V_{CC}=-5.0V$ $I_O=-100\mu A$			-0.3	V
Input Voltage(ON)	$V_{I(on)}$	$V_O=-0.3V$ $I_O=-1.0mA$	-1.4			V

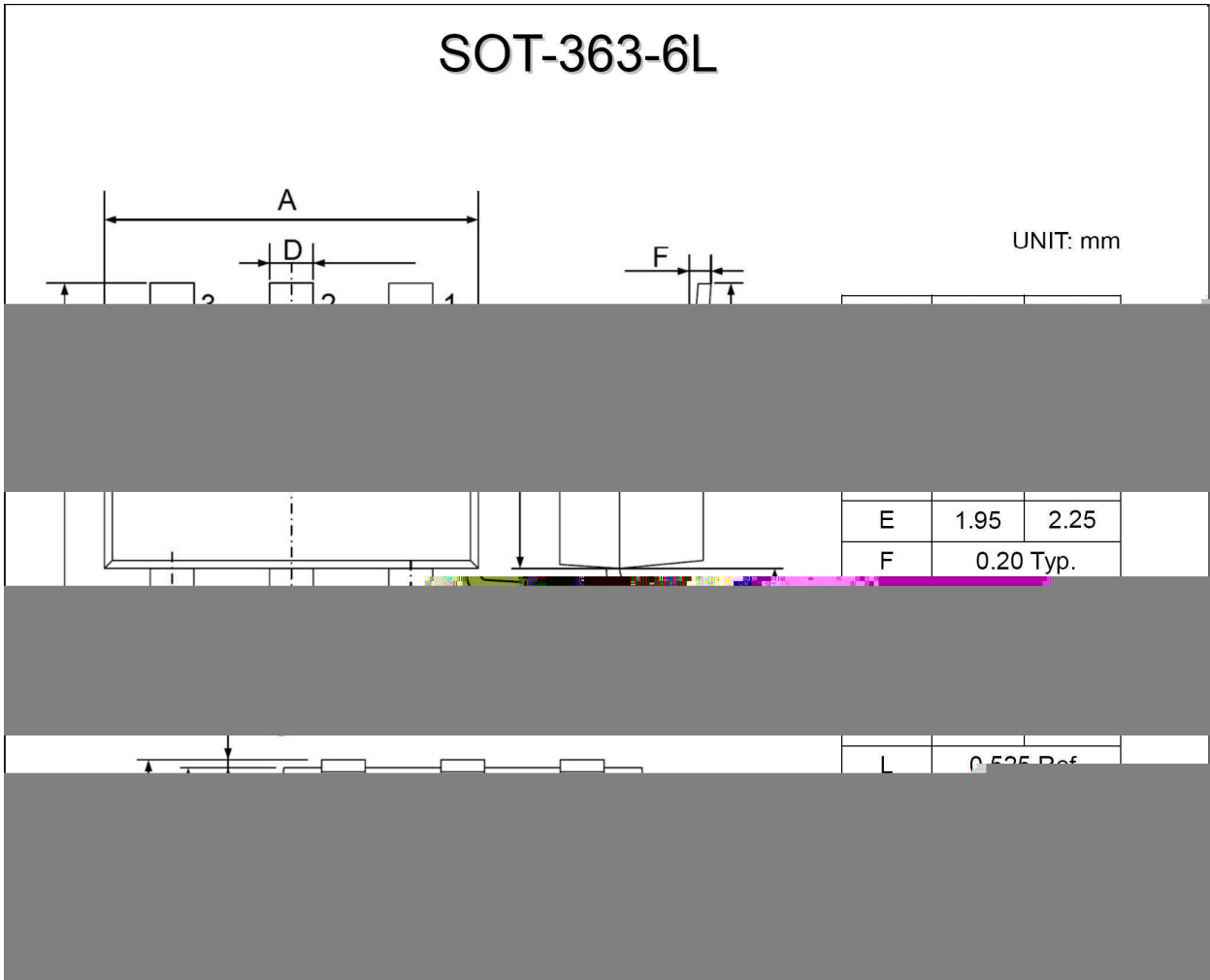
/ Electrical Characteristic Curve(NPN)



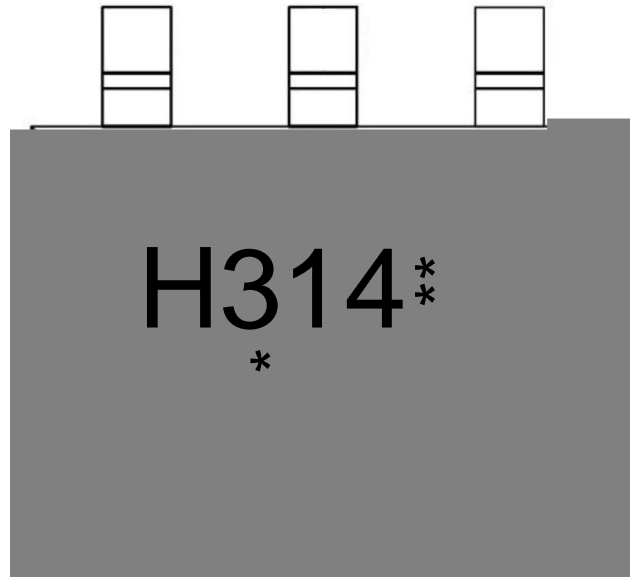
**BRMUN5314WS**

Rev.B Nov.-2021

**/ Package Dimensions**



/ **Marking Instructions**



- " 1"
- H314
- \*\*\*:
- Note:
- "1" Pin
- H314 Product Type Code
- \*\*\*: Lot No. Code, code change with Lot No.



**( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)**


Note:

- |   |         |           |  |
|---|---------|-----------|--|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180°C, Time:60~90sec.   |
| 2 | 245±5   | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | 2       | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec.            |

**/ Resistance to Soldering Heat Test Conditions**

260±5°C                      10±1 sec.                      Temp.:260±5°C                      Time:10±1 sec

**/ Packaging SPEC.**

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱 /